BONDING THE STARS





Digital Ultrasonic Generator D-USG X

>> Features

- Universal Ultrasonic generator for all types of wire bonding and other joining processes; entirely digitally controlled
- Large range of frequencies and power
- Usable for all standard transducers from all suppliers
- Control and frequency generation by digital signal processor (DSP)
- Software-based control algorithms of any kind, such as voltage, current or power regulation; optionally also combinations of these
- Multiple input options from simple up to dynamic real-time templates of complicated pulse profiles such as bursts, ramps or temper phases
- Powerful process monitoring by output of time course of frequency, phase, voltage and current at the transducer
- Transducer-Health-Check: Diagnosis of transducer state by frequency sweep to find position and quality of resonance; simple monitoring of correct mounting of transducer and bond tool
- Optional: Entirely novel control features by custom-tailored algorithms to evaluate process parameter outputs

D-USG X

Thanks to its completely digital concept, our D-USG X is the most versatile ultrasonic generator for wire bonders on the market.

It works with all standard transducers, with all wire types and also with ribbon bonds.

Versatile control options allow the use with practically all wire bonders. In addition, an extensive range of process data are recorded, providing extremely powerful analytical tools for quality assurance.

The transducer diagnostics make it simple and rapid to diagnose the state of transducer and bond tool.

>> Specification

Ultrasonic output Frequency range: 20 – 200 kHz

Power: load-dependent, limited to 50 W (optionally higher)

Control mode Voltage, current, power or customer-specific algorithms

Input options USB-C for configuration and non-time-critical bonds

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8-Bit-parallel input by 26-pin-flat cable for real-time applications

and arbitrary pulse profiles

Optional: Fieldbus to integrate into F&S BONDTEC machines

Transducer connector 25-pin DSUB-plug

Power supply 100-240 VAC 50-60 Hz

C14 power cable socket Fuse: 2x 2AT 5x20 mm

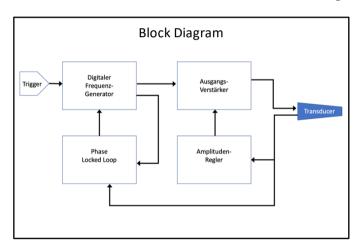
Dimensions, weight 29.5 x 9 x 22.5 cm (W x H x D); 4.30 kg

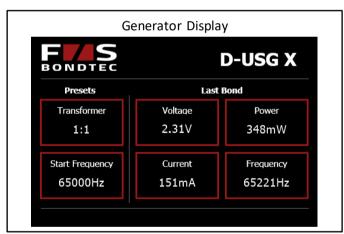
>> User Interface

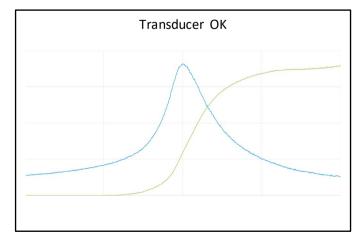
Status display Display of settings and informations to last US pulse

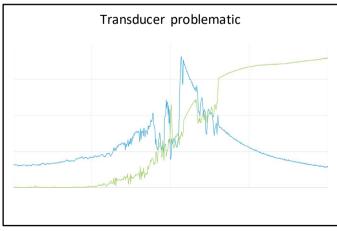
LEDs: BOND, LOCKED & ERROR Test Button for ultrasonic pulse

Hardware monitor Host Software to configure the D-USG X (Windows 10 / 11)









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